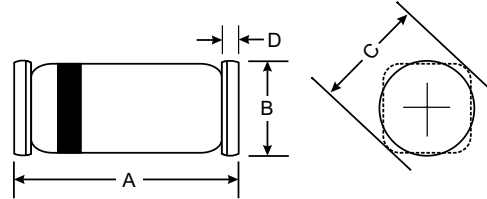


Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance
- Outline Similar to JEDEC 213AA



Mechanical Data

- Case: QuadroMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking: Cathode Band Only
- Weight: 0.034 grams (approx.)

QuadroMELF		
Dim	Min	Max
A	3.3	3.7
B	1.4	1.6
C	1.7Ø Typical	
D	0.3 Typical	
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	75	V
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 1)	I _{FM}	300	mA
Average Rectified Output Current (Note 1)	I _O	150	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0µs	I _{FSM}	2.0	A
Power Dissipation	P _d	500	mW
Thermal Resistance Junction to Ambient Air (Note 1)	R _{θJA}	300	K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +175	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Maximum Forward Voltage	V _{FM}	—	1.0	V	I _F = 50mA
Maximum Peak Reverse Current	I _{RM}	—	25 50 5.0	nA µA µA	V _R = 20V V _R = 20V, T _j = 150°C V _R = 75V
Junction Capacitance	C _j	—	4.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, V _R = 6V, R _L = 100Ω

Notes: 1. Valid provided that electrodes are kept at ambient temperature.

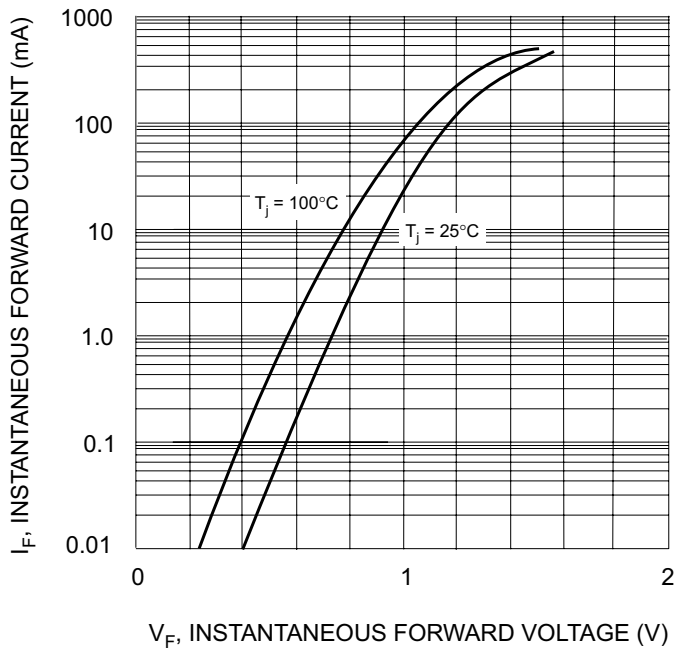


Fig. 1 Forward Characteristics

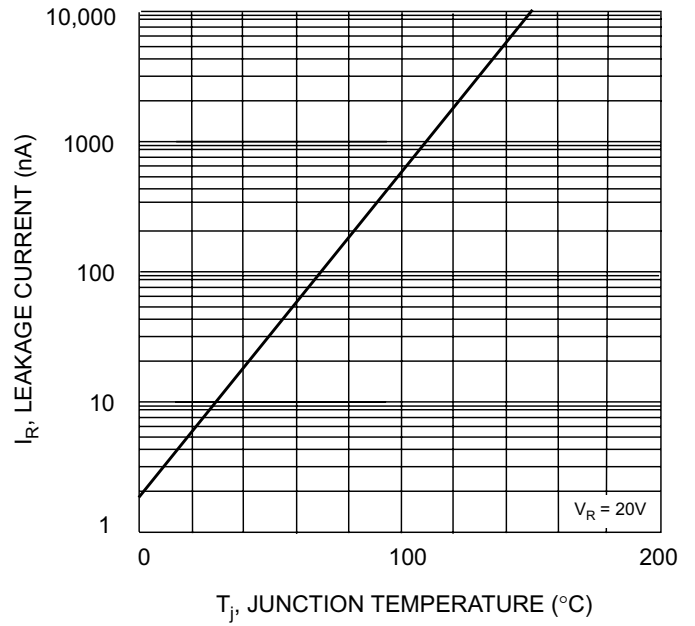


Fig. 2 Leakage Current vs Junction Temperature